



PATENT

Attorney Docket No. ME-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
Serial No. : 10/050,507
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
Group Art Unit : 2812
Confirmation No. : 7687

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CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

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Assistant Commissioner for Patents
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PRELIMINARY AMENDMENT

Sir:

Prior to substantive examination, Applicant requests the following amendments be made in the application.

IN THE CLAIMS

Please amend the claims as shown in the attached replacement sheets submitted under 37 C.F.R. § 1.121(c). A blacklined version is enclosed to illustrate the amendments to the claims.

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01 FC:1202 558.00 OP
02 FC:1201 504.00 OP

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